# The Residual Bi-2212 Intergrowth Distribution in HighJ<sub>c</sub> Tapes and its Origins in the insitu Conversion Process Terry Holesinger

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# Only the Bi-2223 grain next to the silver sheath was free or nearly free of Bi-2212 intergrowths. (FY2002)

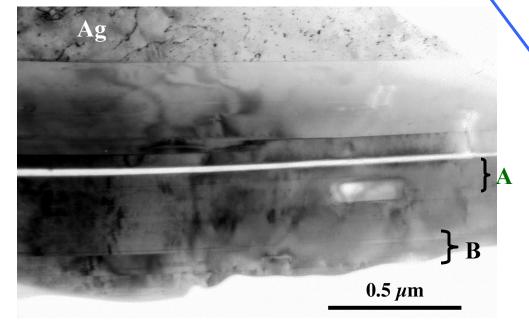
Single Bi-2212

intergrowth

 Spatially non-uniform distribution of intergrowths.

• AMSC production tape with AHT (post anneal)  $I_c = 163 \text{ A}, J_c(S.F., 77K) = 47.7 \text{ kA/cm}^2$ 

Double Bi-2212 intergrowth



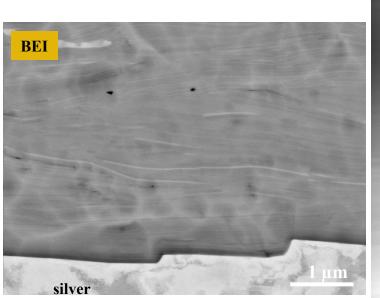
Bi-2234/Bi-2212 intergrowths

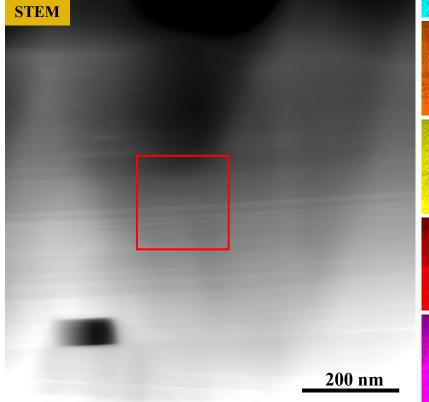


# SEM and STEM reveal significant amounts of residual Bi-2212 in the very high-J<sub>c</sub> sample (27 kA/cm<sup>2</sup>, 77K, 0.1 T)

 STEM imaging and mapping confirm the SEM backscattered images that show Bi-2212 distributed throughout the filament.

Significant amounts of Bi-2212 left in fully processed tapes.







AMSC multifilamentary tape processed at UW with OP post anneal with  $J_c(0.1T, 77K) = 27 \text{ kA/cm}^2$ 

Sr K

Ca K

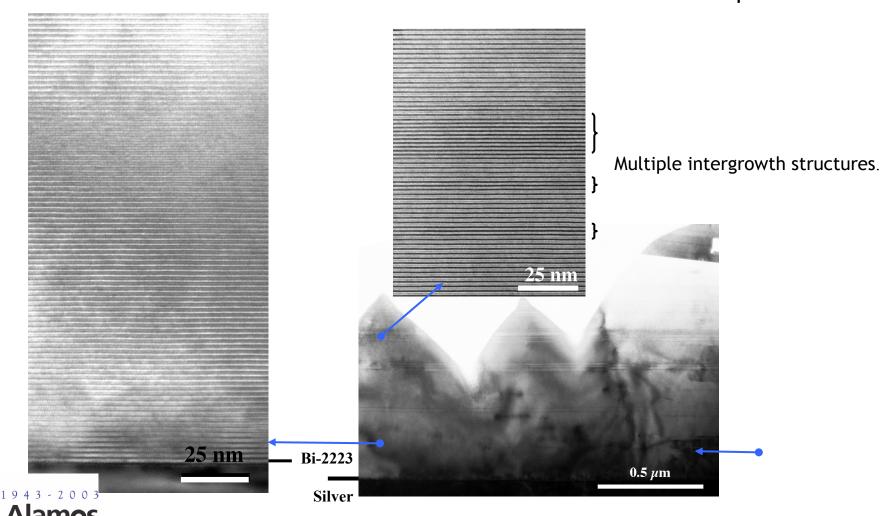
Cu K

Bi L

Pb L

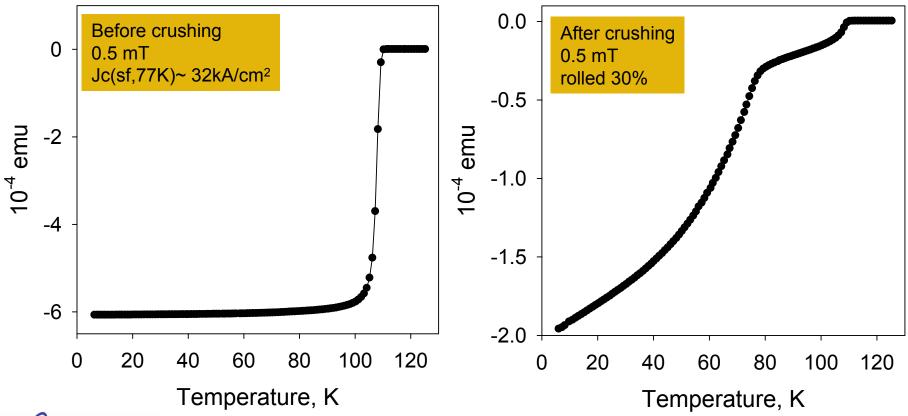
# Although OP processing has pushed $J_c$ above 30 kA/cm<sup>2</sup> (0.1T, 77K), a significant population of Bi-2212 intergrowths remains.

 The grain next to the silver sheath is free of Bi-2212 intergrowths; grains further into the Bi-2223 filament contain Bi-2212 in variable amounts and shapes.



## Crushed SQUID magnetization test supports this microstructural shell model of the Bi-2223 filaments

- Shell of well-formed Bi-2223 coats the inside of the silver sheath.
- Bi-2212 intergrowths and small grains can be found everywhere else in the filament.
- Material segregation from conversion process leaves or traps "unreacted" material in the filament centers.

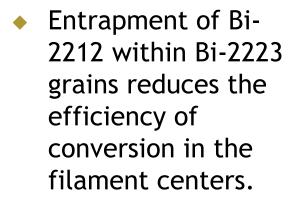


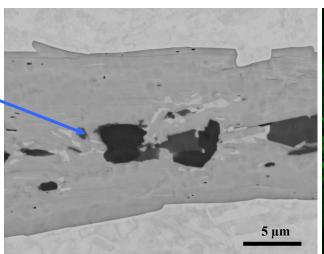


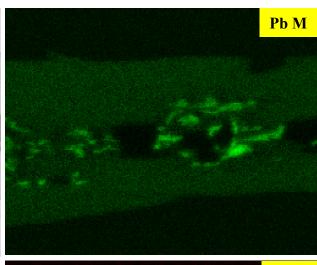
**UW SQUID test** 

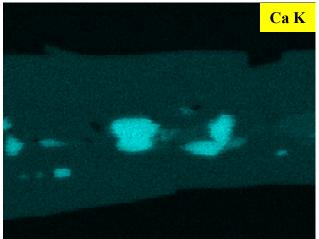
### "Excess" material that could be used to convert residual Bi-2212 into Bi-2223 is trapped in the filament centers after full processing.

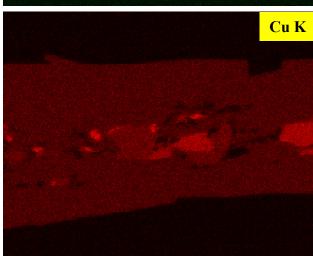
 Residual phases of the 14-24 AEC, 2:1 AEC, and the Pbrich 3221 phase in the middle of the filament.











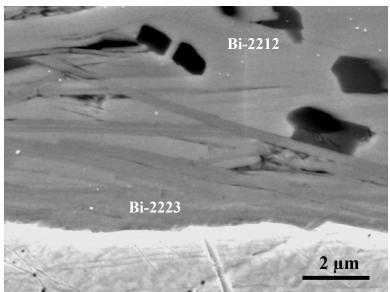


AMSC multifilamentary tape processed at UW with an OP Post Anneal  $J_c(0.1T, 77K) = 27 \text{ kA/cm}^2$ 

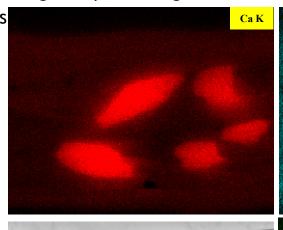
#### The 2212 to 2223 conversion process produces compositional inhomogenities across the filaments right from its early stages

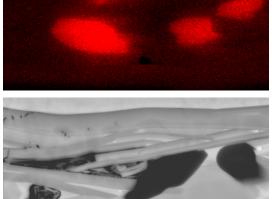
Preferential growth from the silver combined with anisotropic growth rates define a growth front which rapidly decays into a jumble of Bi-2223 grains protruding into the filament center.

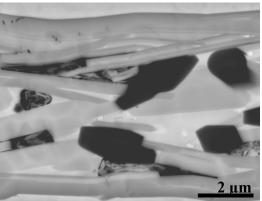
Bi-2212 trapping by growing Bi-2223 grains

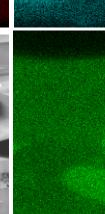


AMSC Bi-2223 tape after 6 hours at 825°C in 8%O<sub>2</sub>.









AMSC Bi-2223 tape quenched in oil after 640 min at 827°C in 8%  $O_2$ .

#### The distribution of residual Bi-2212 intergrowths within the grains starts with the Bi-2223 precipitation process from the partial melt.

Intergrowths in the Bi-2223 grains are continuous and their density is directly proportional to the distance from the liquid phase.

The conversion process ultimately determines the overall distribution of residual Bi-2212

in fully processed tapes.

